

ABSTRACT

The present invention relates to a polishing apparatus for polishing a workpiece to be polished, such as a semiconductor wafer, to a flat mirror finish. The polishing apparatus comprises a polishing table having a polishing surface, and a top ring, and the workpiece to be polished is interposed between the polishing table and the top ring and pressed at a predetermined pressure to polish the workpiece.

10 The polishing apparatus comprises at least two dressing units for dressing the polishing surface by being brought into contact with a surface of a polishing cloth.

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